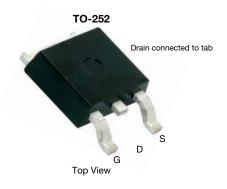
SUD90330E

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Vishay Siliconix

N-Channel 200 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY		
V _{DS} (V)	200	
$R_{DS(on)}$ max. (Ω) at V_{GS} = 10 V	0.0375	
$R_{DS(on)}$ max. (Ω) at V_{GS} = 7.5 V	0.0422	
Q _g typ. (nC)	21	
I _D (A)	35.1	
Configuration	Single	

FEATURES

- ThunderFET[®] power MOSFET
- Low R_{DS} Q_g figure-of-merit (FOM)
- Maximum 175 °C junction temperature
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Synchronous rectification
- Power supplies
- DC/AC inverter
- DC/DC converter
- Solar micro inverter
- Motor drive switch

ORDERING INFORMATION		
Package	TO-252	
Lead (Pb)-free and halogen-free	SUD90330E-GE3	

ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	200	V
Gate-source voltage		V _{GS}	± 20	v
Continuous durin ourrent	T _C = 25 °C		35.8	
Continuous drain current	T _C = 125 °C	- I _D	20.7	
Pulsed drain current (t = 100 µs)		I _{DM}	70	A
Continuous source-drain diode current		IS	12.5	
Single pulse avalanche current ^a		I _{AS}	33	
Single pulse avalanche energy ^a	L = 0.1 mH	E _{AS}	54.45	mJ
Maximum power dissipation	T _C = 25 °C		125 ^b	14/
	T _C = 125 °C	PD	41.7 ^b	W
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	*0
Soldering recommendations (peak temperature) ^c			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	MAXIMUM	UNIT
Maximum junction-to-ambient (PCB mount) ^c		R _{thJA}	40	°C/W
Maximum junction-to-case (drain)	Steady state	R _{thJC}	1.2	0/10

Notes

a. Duty cycle \leq 1 %

b. See SOA curve for voltage derating

c. When mounted on 1" square PCB (FR4 material)

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COMPLIANT

HALOGEN

FREE

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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	1		ł.				
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	200	-	-	V	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2	-	4	V	
Gate-source leakage	I _{GSS}	$V_{DS}=0~V,~V_{GS}=\pm~20~V$	-	-	250	nA	
		$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μΑ	
Zero gate voltage drain current	I _{DSS}	V_{DS} = 200 V, V_{GS} = 0 V, T_{J} = 125 $^{\circ}\text{C}$	-	-	150		
		V_{DS} = 200 V, V_{GS} = 0 V, T_{J} = 175 $^{\circ}\text{C}$	-	-	5	mA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	20	-	-	Α	
Drain acurac an atota registernes à	D	V _{GS} = 10 V, I _D = 12.2 A	-	0.0312	0.0375		
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, \text{ I}_{D} = 11.5 \text{ A}$	-	0.0337	0.0422	Ω	
Forward transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 10 A	-	28	-	S	
Dynamic ^b	•			•	•	•	
Input capacitance	C _{iss}		-	1172	-		
Output capacitance	C _{oss}	V _{DS} = 100 V, V _{GS} = 0 V, f = 1 MHz	-	150	-	pF	
Reverse transfer capacitance	C _{rss}		-	11	-		
Total gate charge	Qg		-	21	32		
Gate-source charge	Q _{gs}	V_{DS} = 100 V, V_{GS} =10 V, I_{D} = 12.2 A	-	6	-	nC	
Gate-drain charge	Q _{gd}		-	5.3	-		
Gate resistance	Rg	f = 1 MHz	0.76	3.8	7.6	Ω	
Turn-on delay time	t _{d(on)}		-	12	24		
Rise time	t _r	$V_{DD} = 100 \text{ V}, \text{ R}_{\text{L}} = 14.2 \Omega, \text{ I}_{\text{D}} \cong 7 \text{ A},$	-	25	50		
Turn-off delay time	t _{d(off)}	$V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$	-	30	50	ns	
Fall time	t _f		-	22	44	1	
Drain-Source Body Diode Characteristi	cs					•	
Pulse diode forward current (t = 100 µs)	I _{SM}		-	-	70	Α	
Body diode voltage	V _{SD}	I _F = 7 A, V _{GS} = 0 V	-	0.8	1.5	V	
Body diode reverse recovery time	t _{rr}		-	111	170	ns	
Body diode reverse recovery charge	Q _{rr}		-	0.51	1	μC	
Reverse recovery fall time	ta	I _F = 7 A, di/dt = 100 A/μs	-	94	-		
Reverse recovery rise time	t _b		-	17	-	ns	
Body diode peak reverse recovery charge	I _{RM(REC)}		-	8.5	17	Α	

Notes

a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$

b. Guaranteed by design, not subject to production testing

c. Independent of operating temperature

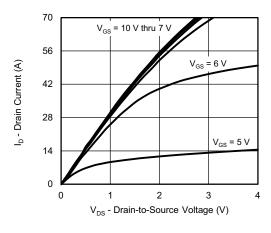
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



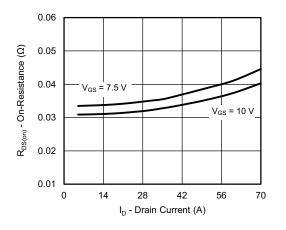
SUD90330E

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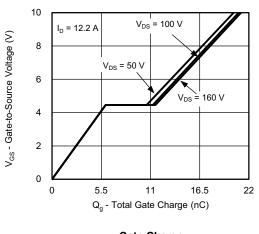
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



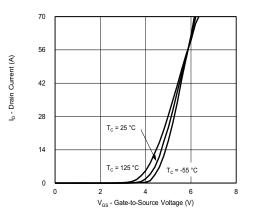




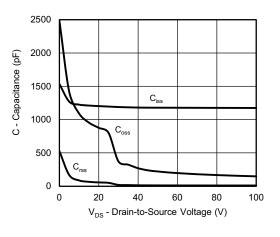
On-Resistance vs. Drain Current and Gate Voltage



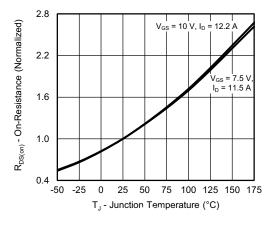
Gate Charge



Transfer Characteristics



Capacitance



On-Resistance vs. Junction Temperature

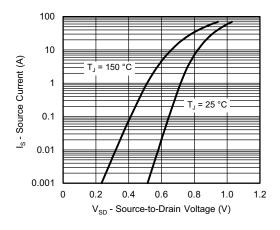
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3 estions contact prostechsuppor Document Number: 74527

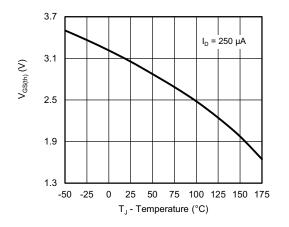
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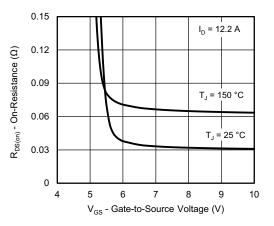
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



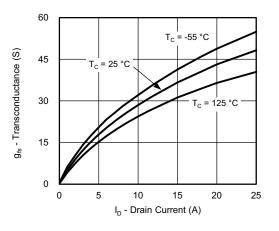
Source-Drain Diode Forward Voltage



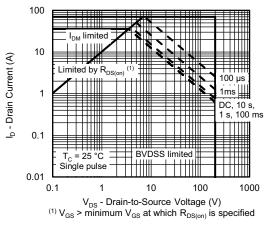
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Transconductance



Safe Operating Area, Junction-to-Ambient

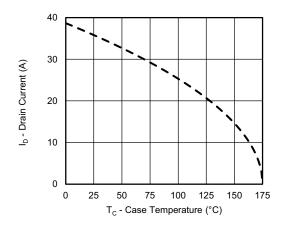
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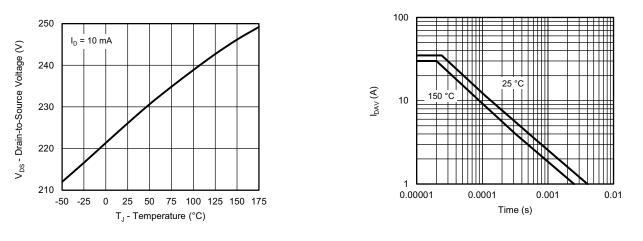
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



Drain Source Breakdown vs. Junction Temperature

Avalanche vs. Time

Note

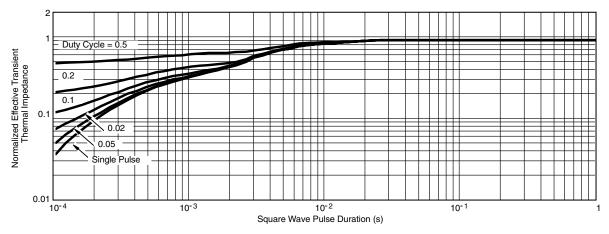
a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

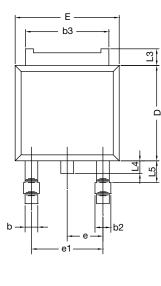
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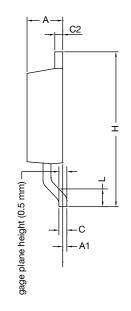


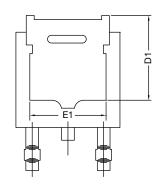


TO-252AA Case Outline

VERSION 1: FACILITY CODE = Y







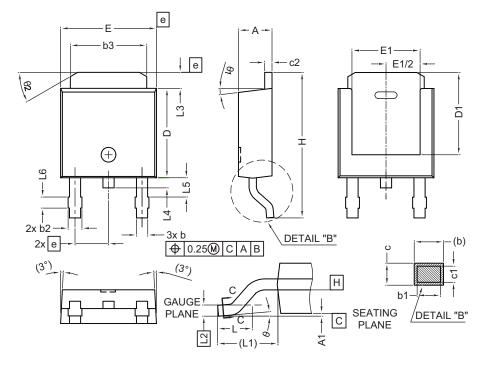
	MILLIMETERS			
DIM.	MIN.	MAX.		
A	2.18	2.38		
A1	-	0.127		
b	0.64	0.88		
b2	0.76	1.14		
b3	4.95	5.46		
С	0.46	0.61		
C2	0.46	0.89		
D	5.97	6.22		
D1	4.10	-		
E	6.35	6.73		
E1	4.32	-		
Н	9.40	10.41		
е	2.28	BSC		
e1	4.56	4.56 BSC		
L	1.40	1.78		
L3	0.89	1.27		
L4	-	1.02		
L5	1.01	1.52		

Note

• Dimension L3 is for reference only



VERSION 2: FACILITY CODE = N



	MILLIMETERS		
DIM.	MIN.	MAX.	
A	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	-	
E	6.35	6.73	
E1	4.32 -		
e	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14 1.49		
L6	0.65	0.85	
θ	0°	10°	
θ1	0° 15°		
θ2	25° 35°		

Notes

• Dimensioning and tolerance confirm to ASME Y14.5M-1994

• All dimensions are in millimeters. Angles are in degrees

• Heat sink side flash is max. 0.8 mm

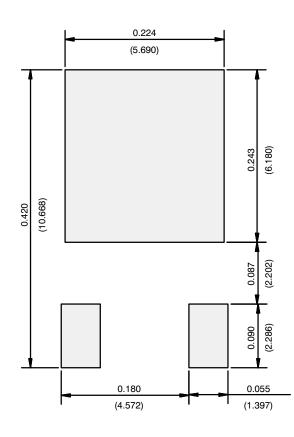
Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022 DWG: 5347

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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